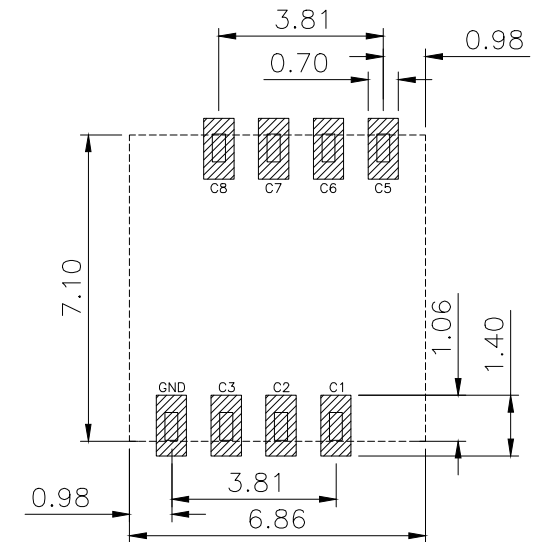
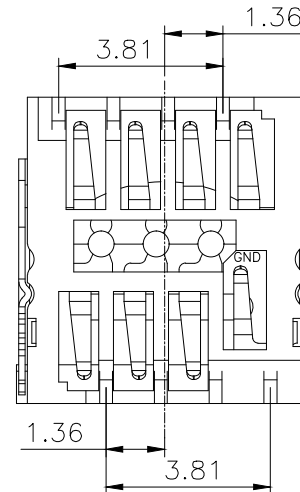
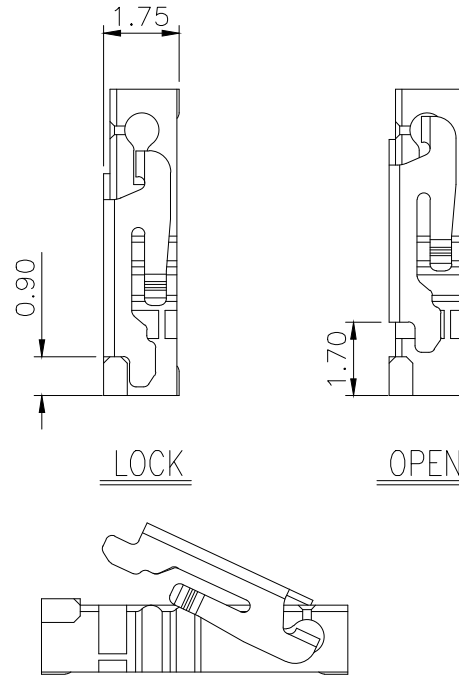
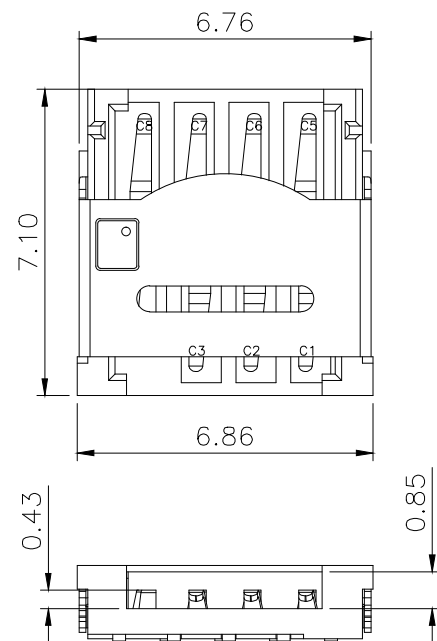
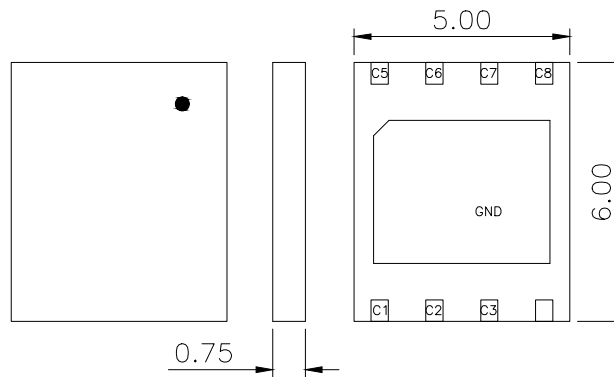
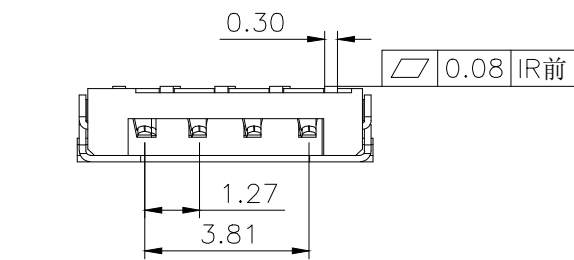


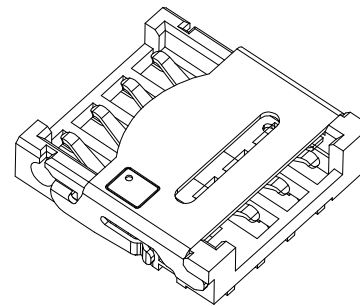
REV.	ECN.NO.	MODIFY.CONTENT	DATE
A0		NEW	2021/05/28



■ CIRCUIT TRACE KEEP OUT AREA  
■ SMT SOLDER AREA  
THERE SHOULD NOT BE ANY CIRCUITRIES  
IN THE LAYOUT SPACE OF THE PRODUCTS.  
RECOMMENDED PCB LAYOUT  
GENERAL TOLERANCE ±0.05

- 1) MATERIAL:  
1.1 HOUSING: LCP, UL94-V0, COLOR: BLACK  
1.2 OCONTACT: C5210-H  
1.3 SHELL: SUS304-H
- 2) FINISH:  
2.1 TERMINAL: 50 μ" Min. NICKEL PLATED OVERALL  
2.2 CONTACT: GOLD FLASH PLATED ON CONTACT AREA;  
GOLD FLASH PLATED ON SOLDER TAILS;
- 3) ELECTRICAL CHARACTERISTICS  
RATING CURRENT : 0.5A MAX.  
CONTACT RESISTANCE : 50 mΩ MAX  
DIELECTRIC WITHSTANDING : 500V AC MIN.  
INSULATION RESISTANCE: 1000 MΩ MIN.

序号	触点信号	解释
1	VSS	接地
2	NULL	未定义
3	I/O	数据输入/数据端口
4	NULL	未定义
5	NULL	未定义
6	CLK	时钟信号输入端
7	RST	复位信号输入端
8	VDD	供电电压输入端



GENERAL TOLERANCE		DWG NO.			APPD:		Scale	1:1
X.±0.45	x.*±5°	Title	1.75H E SIM CARD 8PIN 掀盖式		CHKD:		UNIT	mm
.X±0.35	.x.*±2°				DR:	Peng		
.XX±0.25	.xx.*±1°	Part NO.	5001B-ESIM175-199		Date	2021/05/28		
.XXX±0.15	.xxx.*±0.5°		东莞市文章济美电子有限公司					
SHEET	1/2							

REV.	ECN.NO.	MODIFY.CONTENT	DATE
A0		NEW	2021.03.05

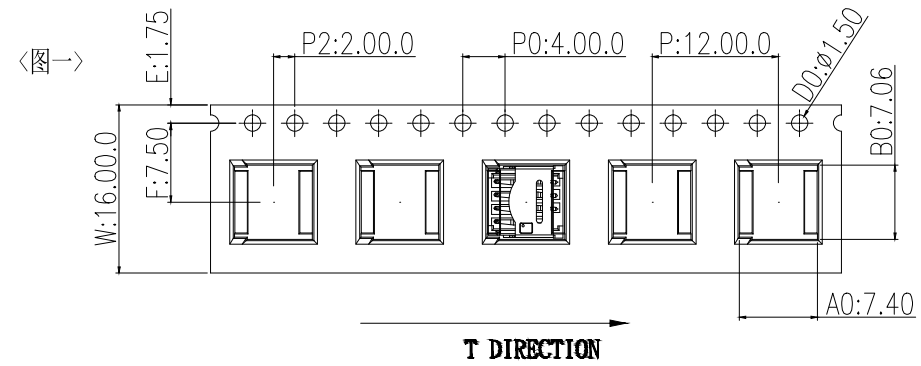
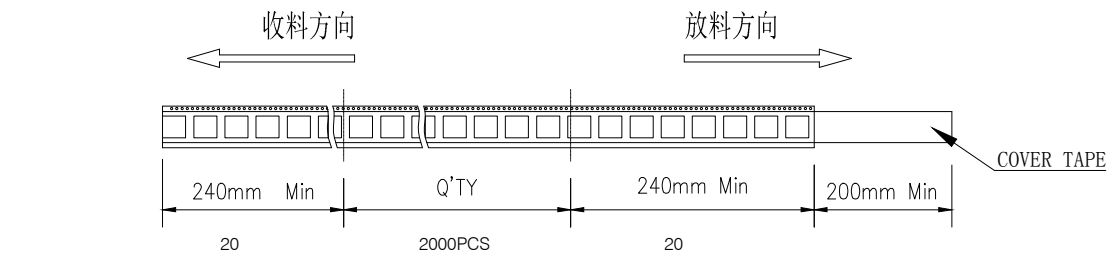
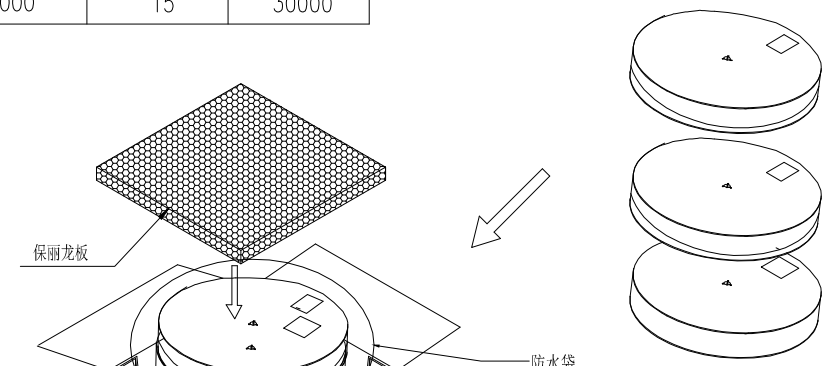


TABLE 1> PACKAGING QUANTITY

QTY/REEL	REEL/CARTON	QTY/CARTON
2000	15	30000

Figure 3: Packaging assembly diagram showing the carrier, carrier tape, and carrier board.



COVER TAPE PEELING FORCE:20gf~100gf

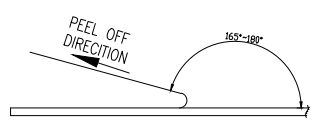
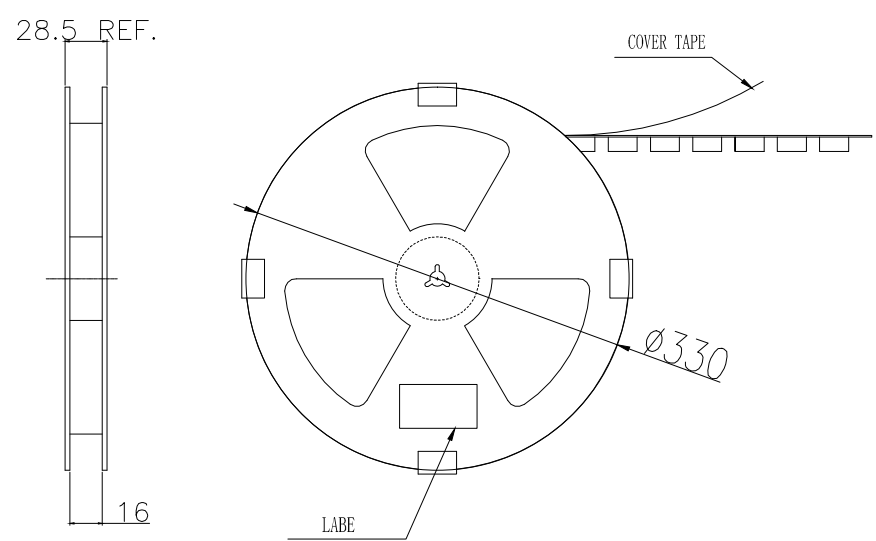
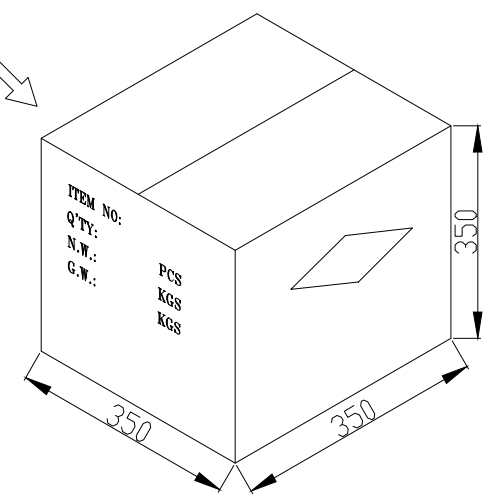


Figure 2: Carrier tape diagram.



NOTE:

- 依<图一>示放置产品于下载中, 每穴放置1PCS产品.
- 包装机包好后, 在REEL的个等分点贴上胶带, 以防止REEL张开, 每REEL贴1PCS标签, 如<图二>示
- 包装数量见如<TABLE 1>示
- 包装成箱见如<图三>示  
箱底放保丽龙板, 再依次将指定数量的卷装产品用防水袋包好放入箱内, 四角分别放入四个三角护板, 最上层再放上保丽龙板.
- 封箱, 在封好的纸箱上按客户要求写上料号, 数量等



GENERAL TOLERANCE		图号	设计	Peng	比例	1:1
X.±0.45	x.*±5°	品名	1.75H E SIM CARD 8PIN 掀盖式	审核	单位	mm
.X±0.35	.x±2°	料号	5001B-ESIM175-199	核准	日期	2021/03/05
.XX±0.25	.xx±1°					
.XXX±0.15	.xxx±0.5°					
页号	2/2	东莞市文章济美电子有限公司				